

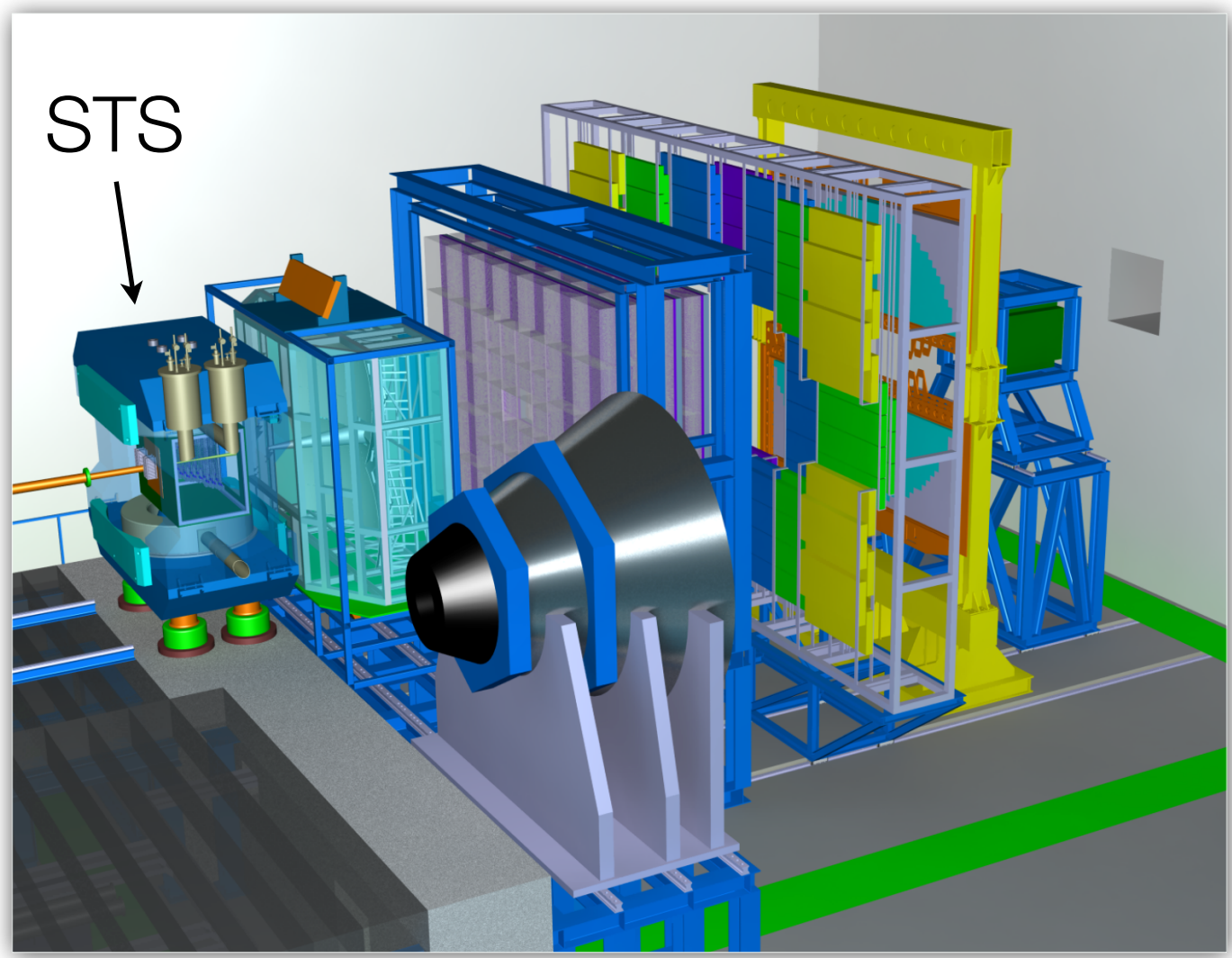


# Quality Assurance and radiation tolerance tests of double-sided silicon sensors for the CBM Silicon Tracking System

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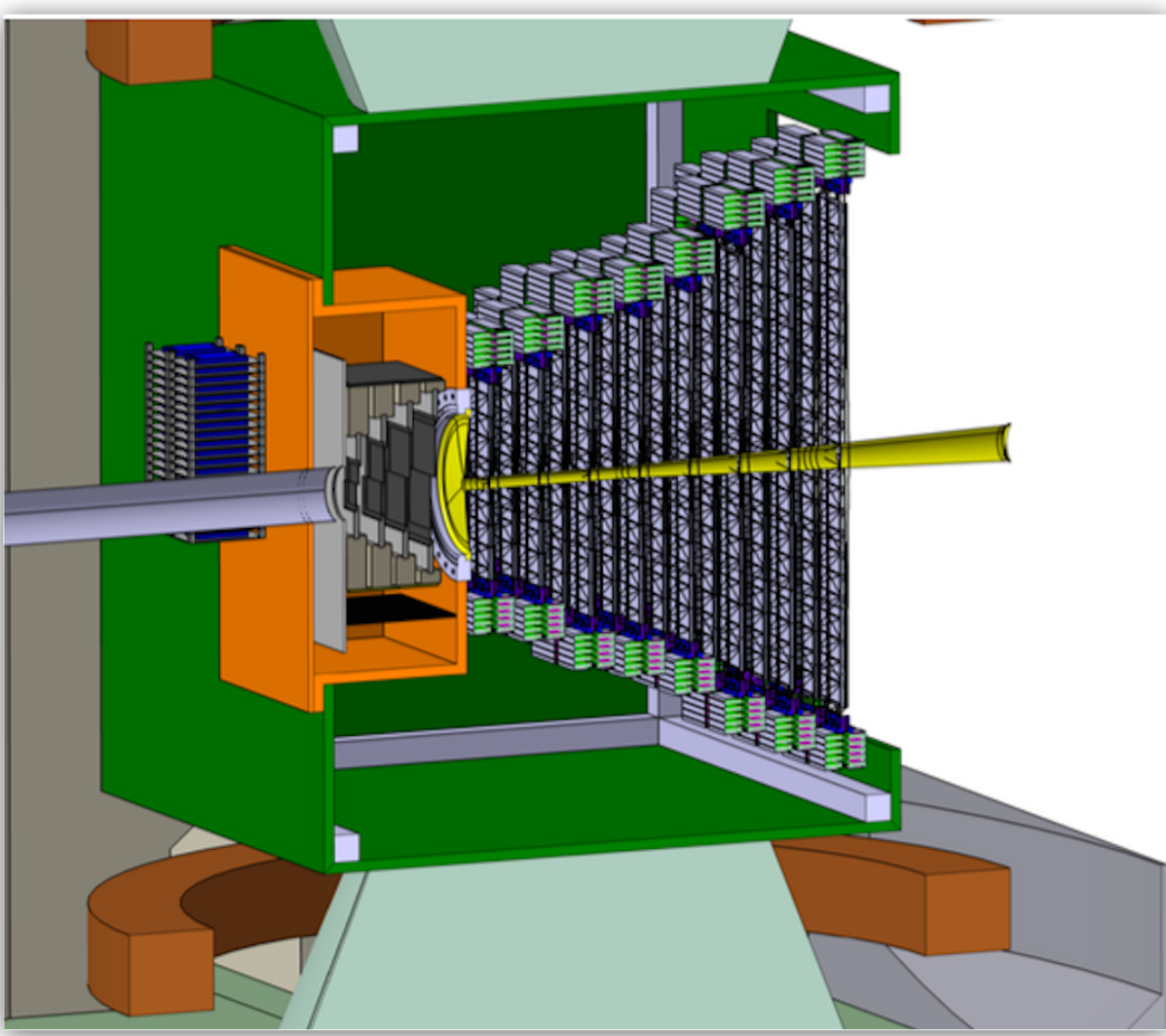


## The Compressed Baryonic Matter experiment at FAIR



3D view of CBM set-up

- Explore the QCD phase diagram (high net-baryonic densities and mid temperatures region);
- Fixed target experiment, collision energies 2-45 AGeV;
- Measuring rare ( $J/\psi$ ), penetrating probes ( $\rho$ ,  $\omega$ ,  $\phi$ ) and multi-strange hyperons.



Silicon Tracking System (STS)

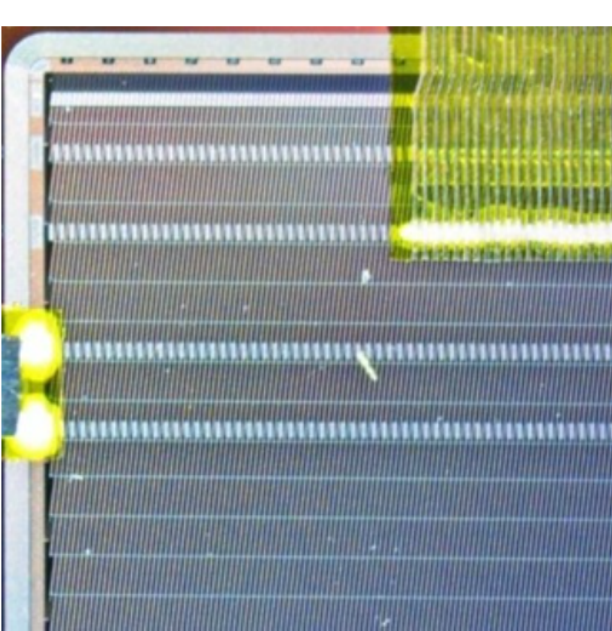
- 8 tracking stations 30 cm downstream the target;
- Reconstruct tracks of charged particles, determine their momenta;
- Constructed with double-sided silicon strip sensors;
- Readout electronics outside of the physics aperture  $2.5^\circ < \theta < 25^\circ$ .



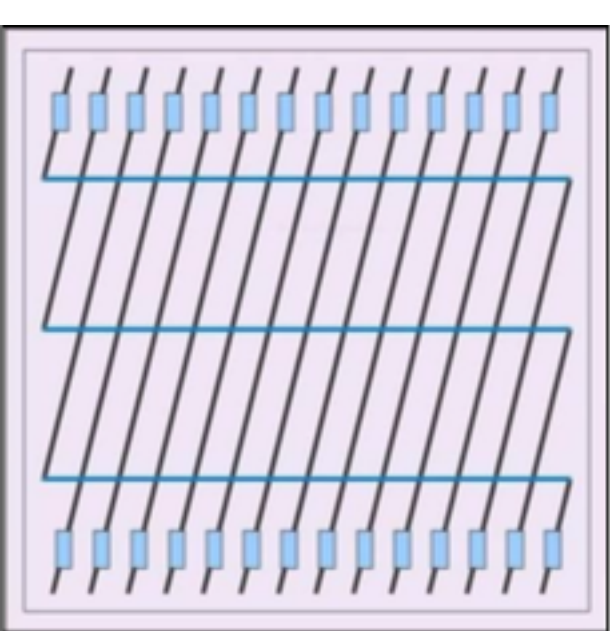
STS Module

A building block of the STS

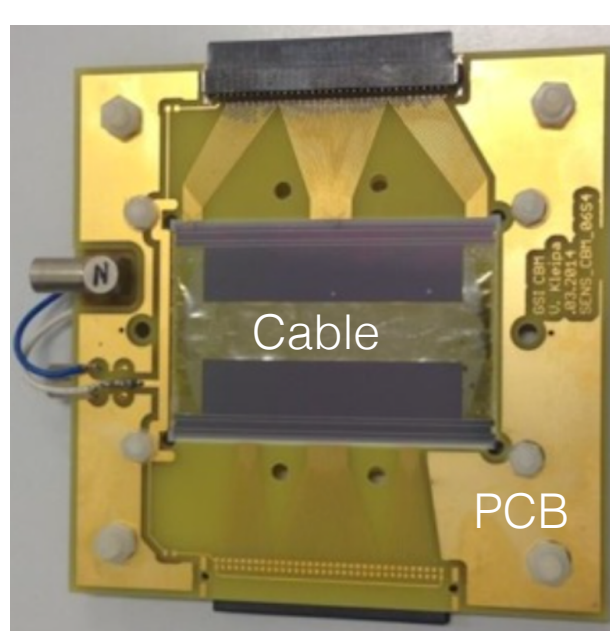
## Double-sided microstrip sensors



CBM prototype sensor corner view

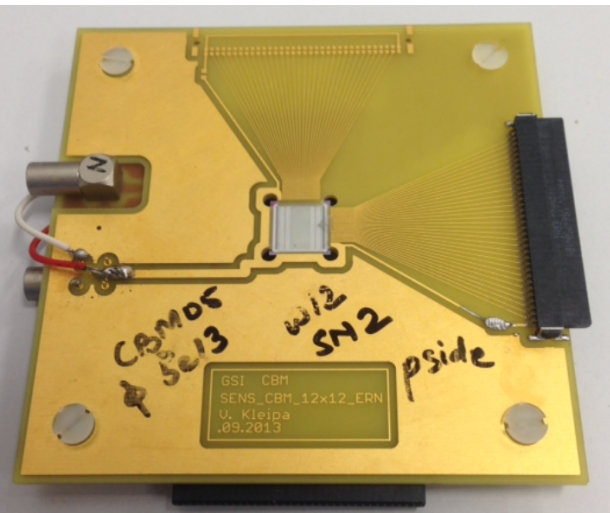


Double-metal interconnection



External microcable interconnection

- $p^+n^-n^+$  silicon structure;
- 58  $\mu\text{m}$  strip pitch;
- 1024 strips per side;
- Stereo angle front-back side  $7.5^\circ$ ;
- Poly-Si biasing structure;
- Integrated AC-coupled readout;
- ~ 1200 will be produced in four sizes;
- baby sensors: orthogonal strips, 50  $\mu\text{m}$  strip pitch, same wafer.



Baby sensor

## Sensor Quality Assurance

### Sensor requirements

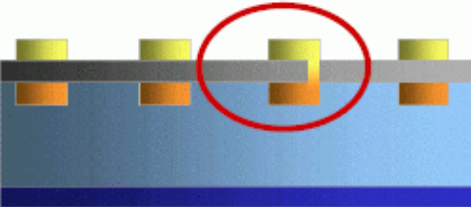
- Provide track reconstruction efficiency ~95% for fast primary tracks;
- ~99% hit efficiency;
- Radiation tolerant up to  $1 \times 10^{14} n_{eq}/\text{cm}^2$ ;
- Full depletion voltage  $< 100\text{ V}$ ;
- Leakage current  $< 8\text{ nA}/\text{strip}/\text{cm}$  at 300V;
- Number of defected strips  $< 1\%$  per sensor.

### Quality Assurance (QA)

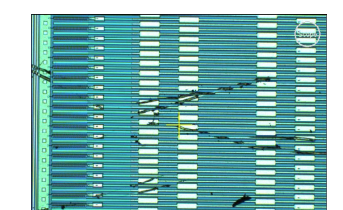
Macroscopic QA:  
I-V and C-V tests.

Microscopic QA:  
Optical inspection;  
Strip quality tests.

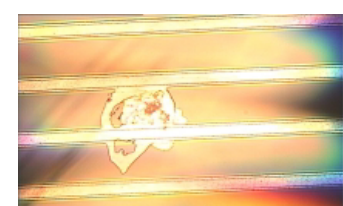
### Strip defects



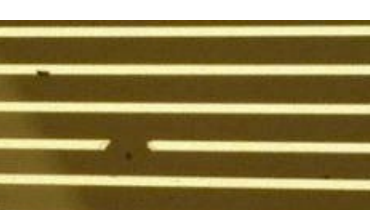
"Pinhole" [1]



Scratches

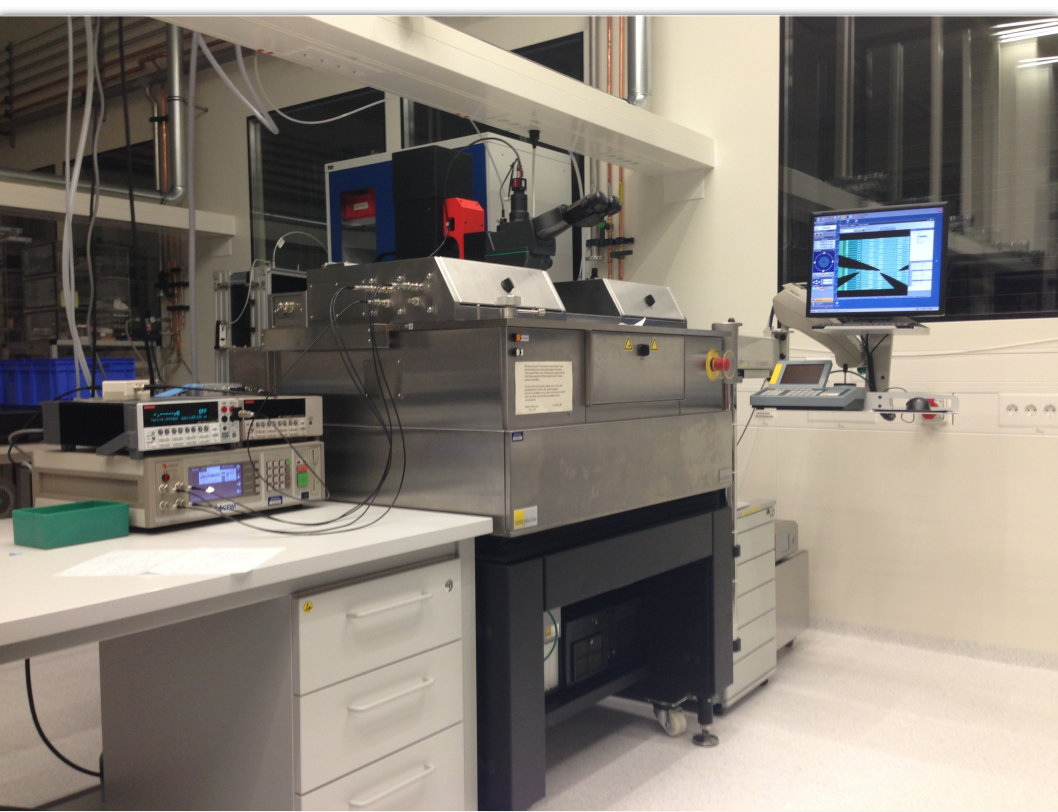


Metal short [1]

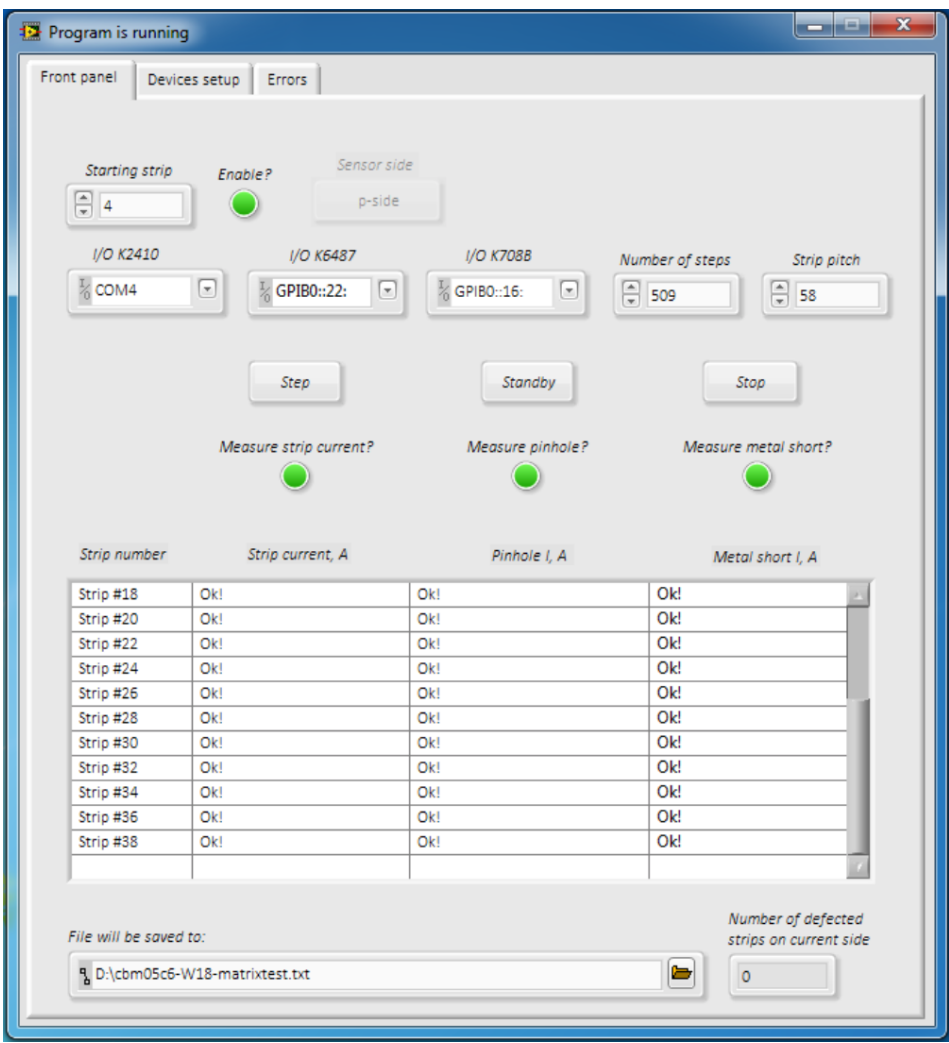


Metal brake [1]

### Setup for Microscopic QA

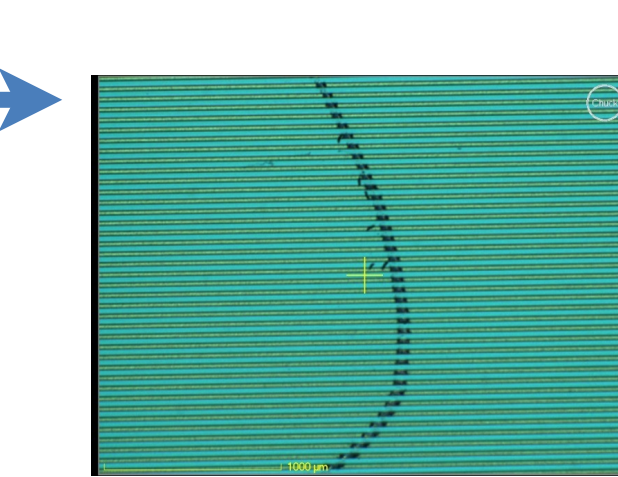
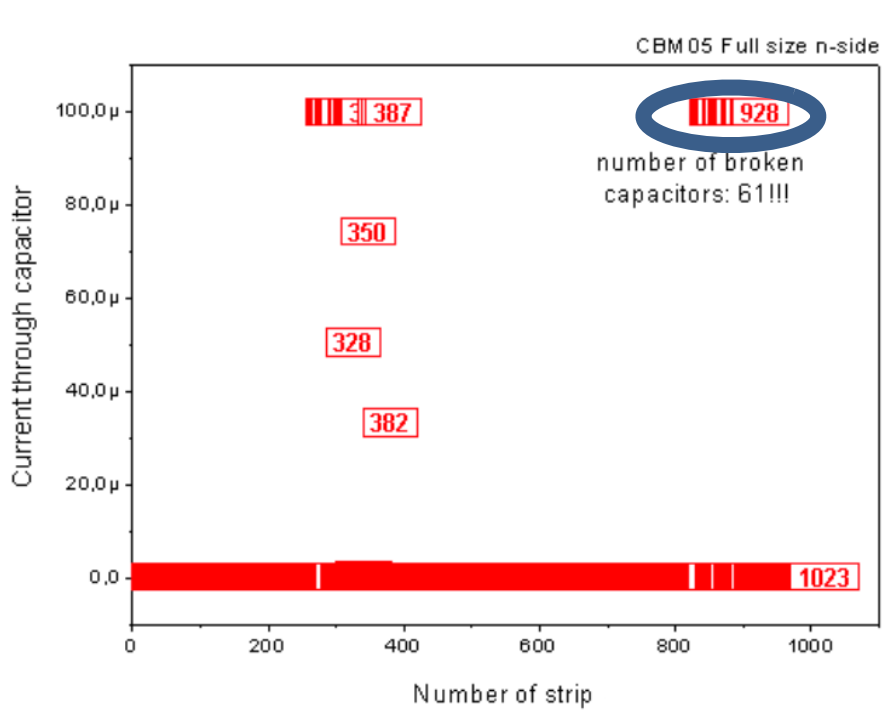


- Cleanroom environment with temperature and humidity control;
- Probe station Süss PA300PS equipped for detailed sensor tests;
- Instruments for the measurement of strip parameters;
- Switching matrix (multiplexer);
- Automated measurements.

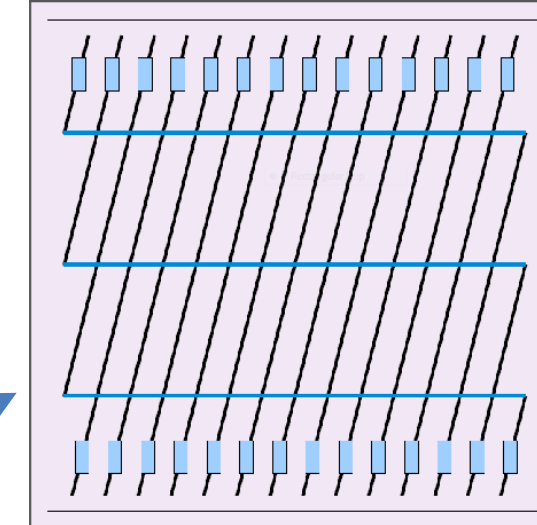
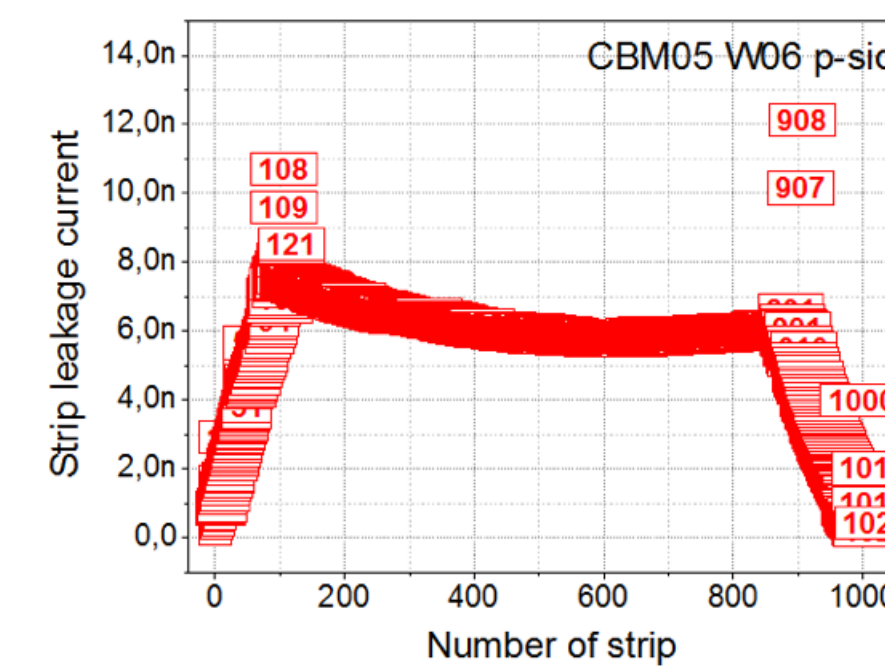


- LabView based software;
- Perform multiple or single tests;
- Check for pinholes, metal shorts, strip current;
- Results shown online and also saved ASCII file;
- 6 seconds per strip (measuring three parameters).

### Software and results



Scratch resulted in large number of pinholes

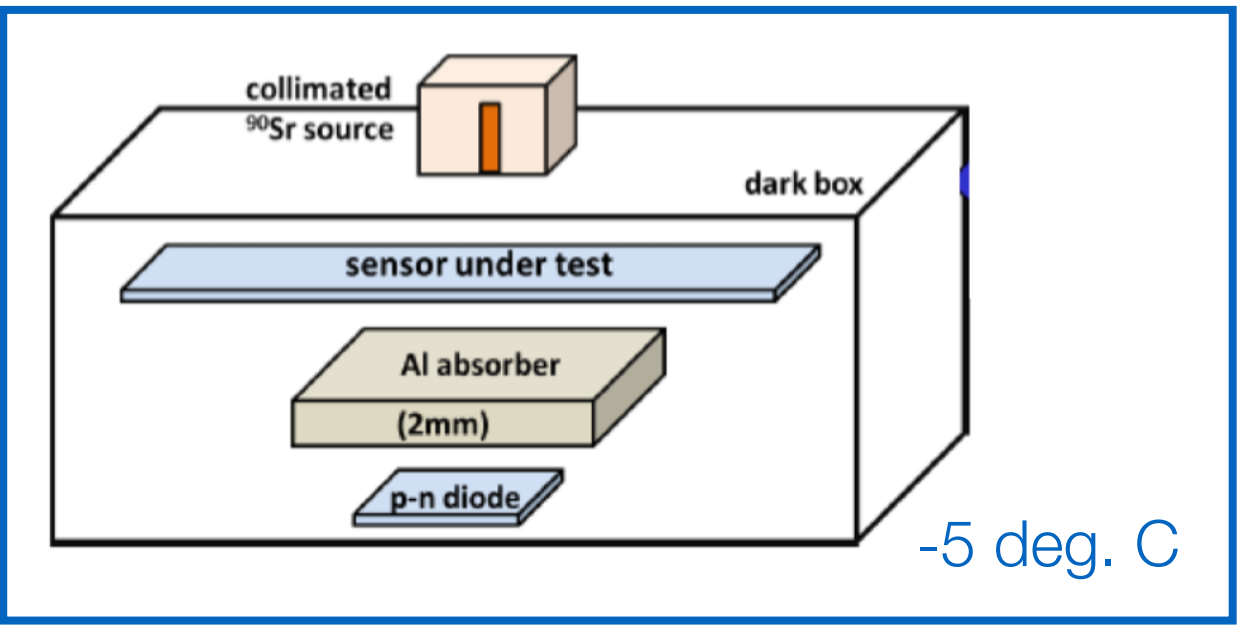


## Sensor radiation tolerance tests

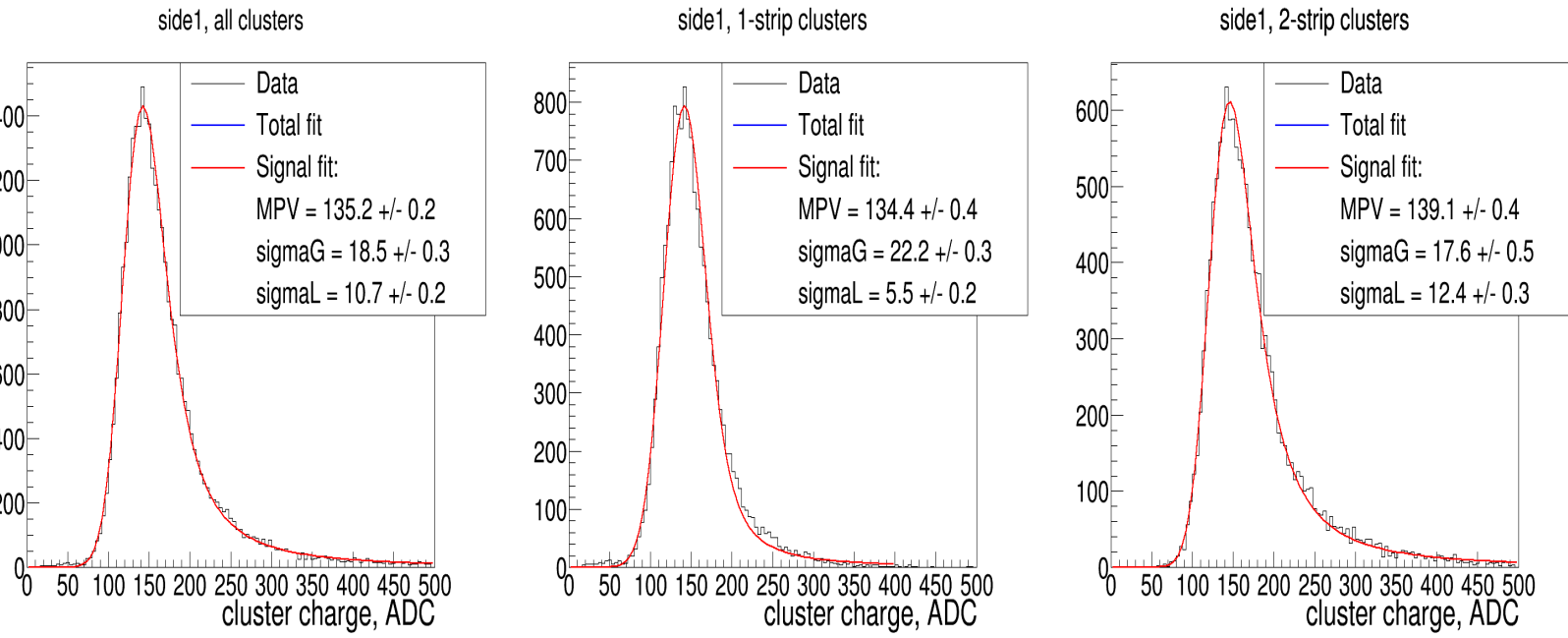
### Aim of the work

- STS's TDR:  $1 \times 10^{14} 1\text{ MeV } n_{eq}/\text{cm}^2$  is the harshest scenario for CBM sensors;
- Baby sensors irradiated:  $1 \times 10^{13}$ ,  $3 \times 10^{13}$ ,  $5 \times 10^{13}$ ,  $8 \times 10^{13}$ ,  $1 \times 10^{14}$ ,  $2 \times 10^{14}$  in TRIGA reactor, IJS, Slovenia;
- Full-size prototypes irradiated:  $2 \times 10^{14}$  at KIT, Germany;
- Monitor parameters:
  1. charge collection;
  2. Full depletion voltage  $V_{fd}$ ;
  3. Leakage current  $I_{leak}$  stability;
  4. charge collection vs annealing;
  5. charge collection for different interconnecting schemes (full-size sensors).

### Setup for charge collection tests

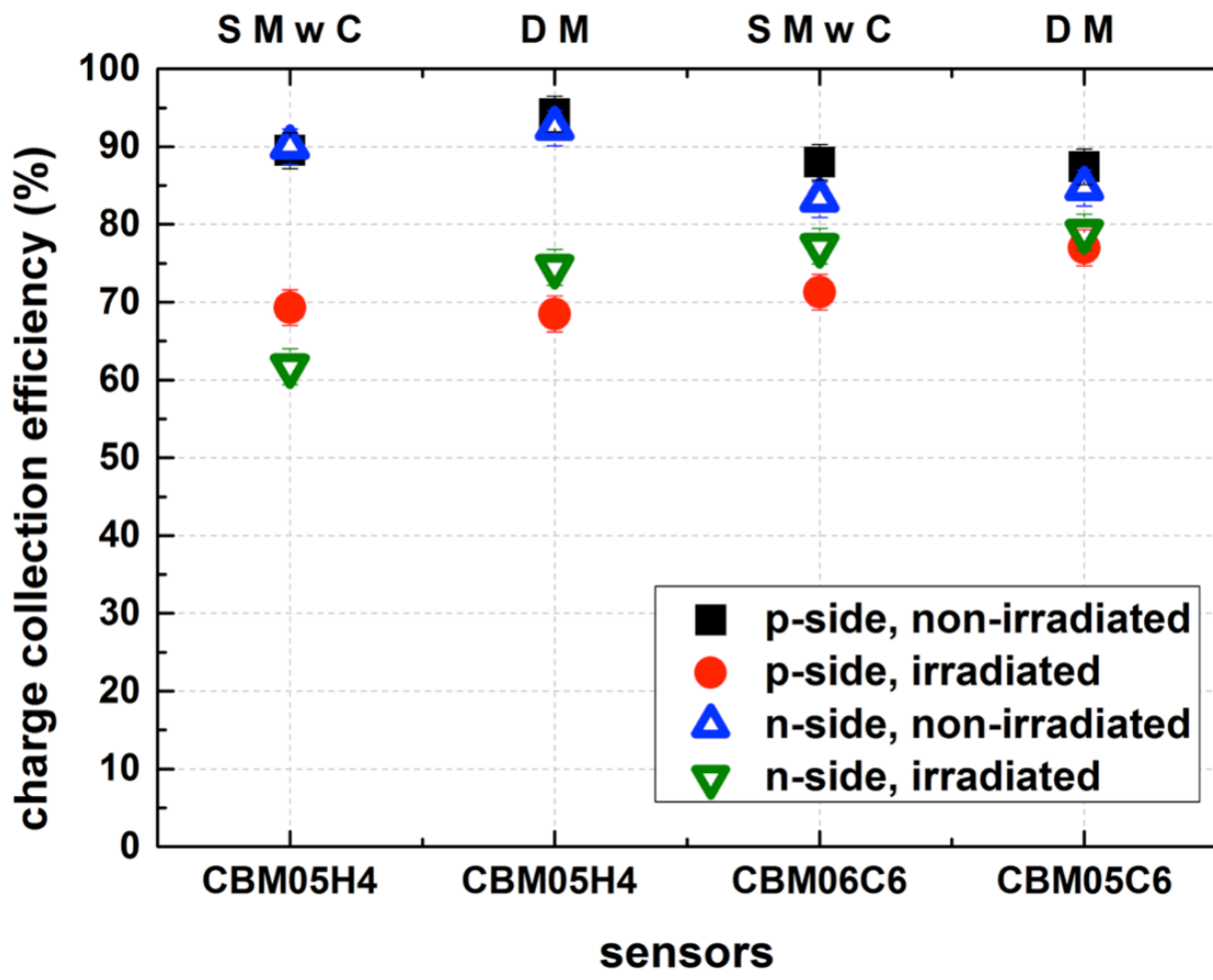


### Charge collection analysis



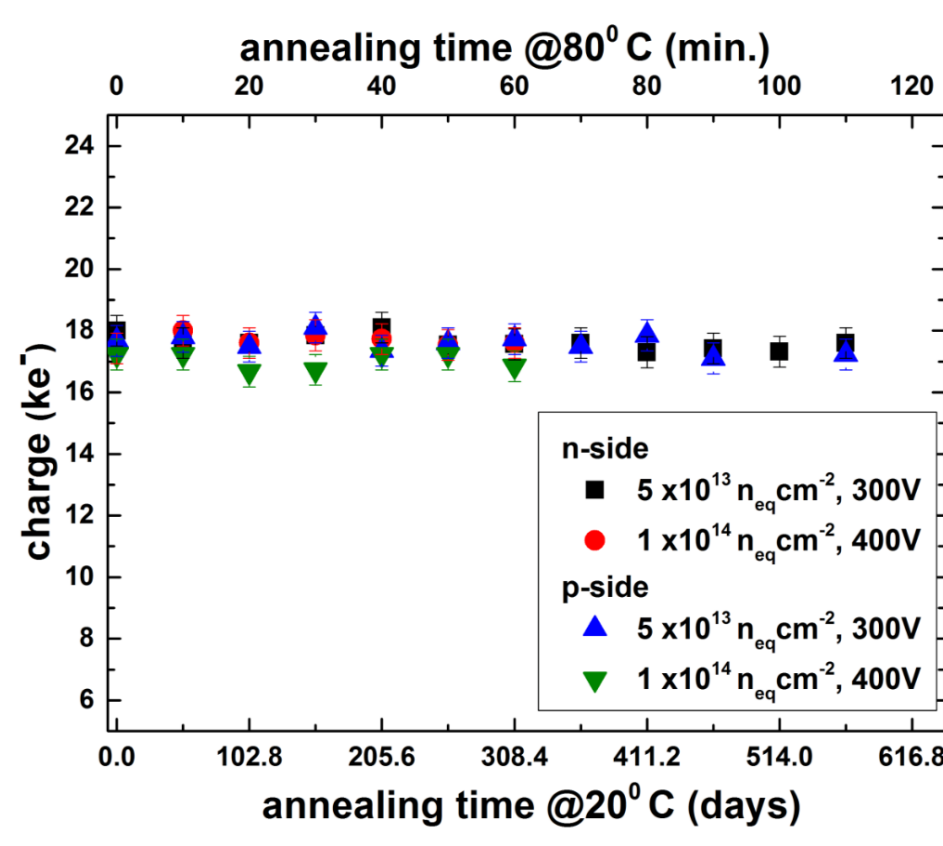
fitting: Landau - Gaussian convolution

### Charge collection vs strip interconnection schemes



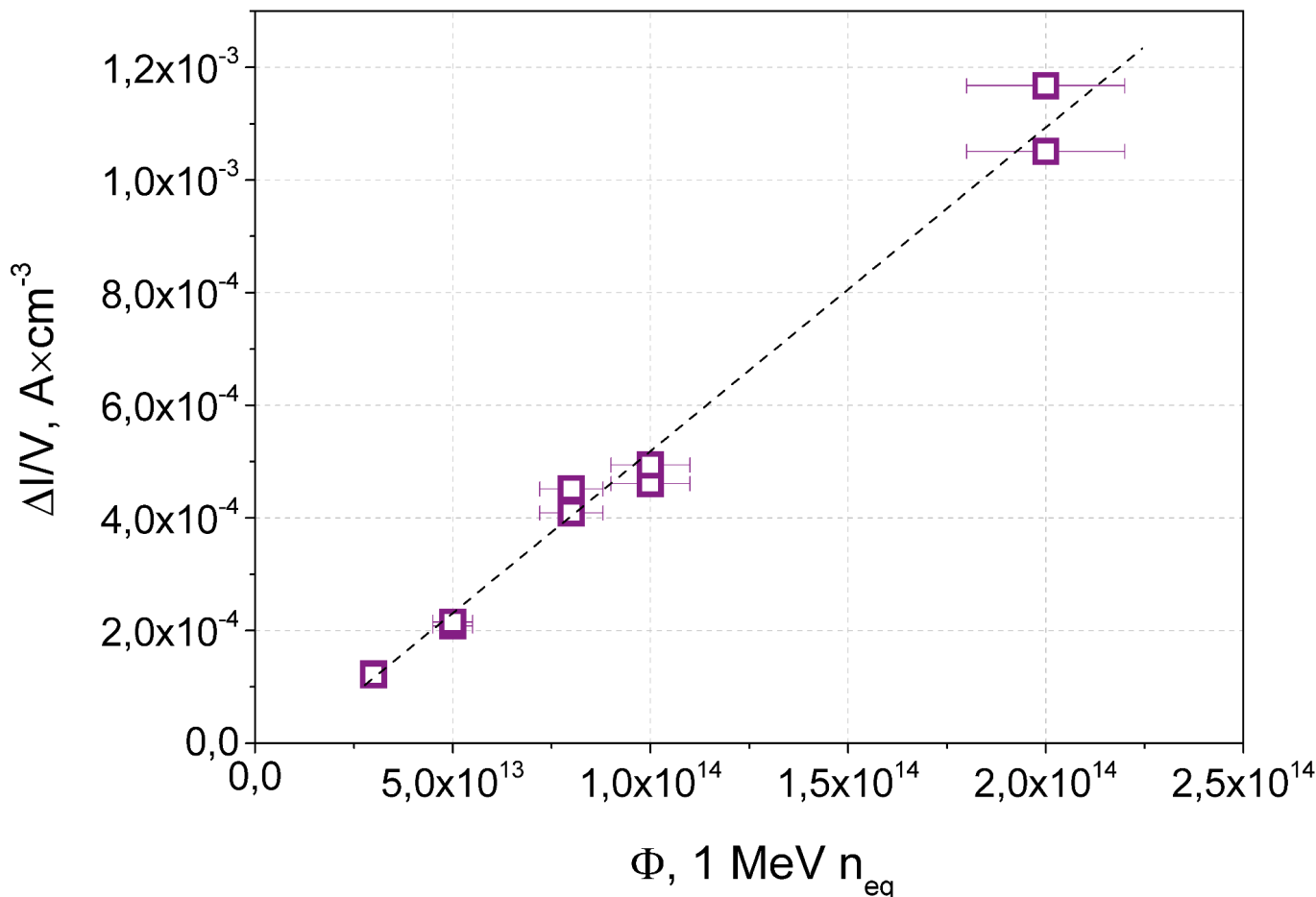
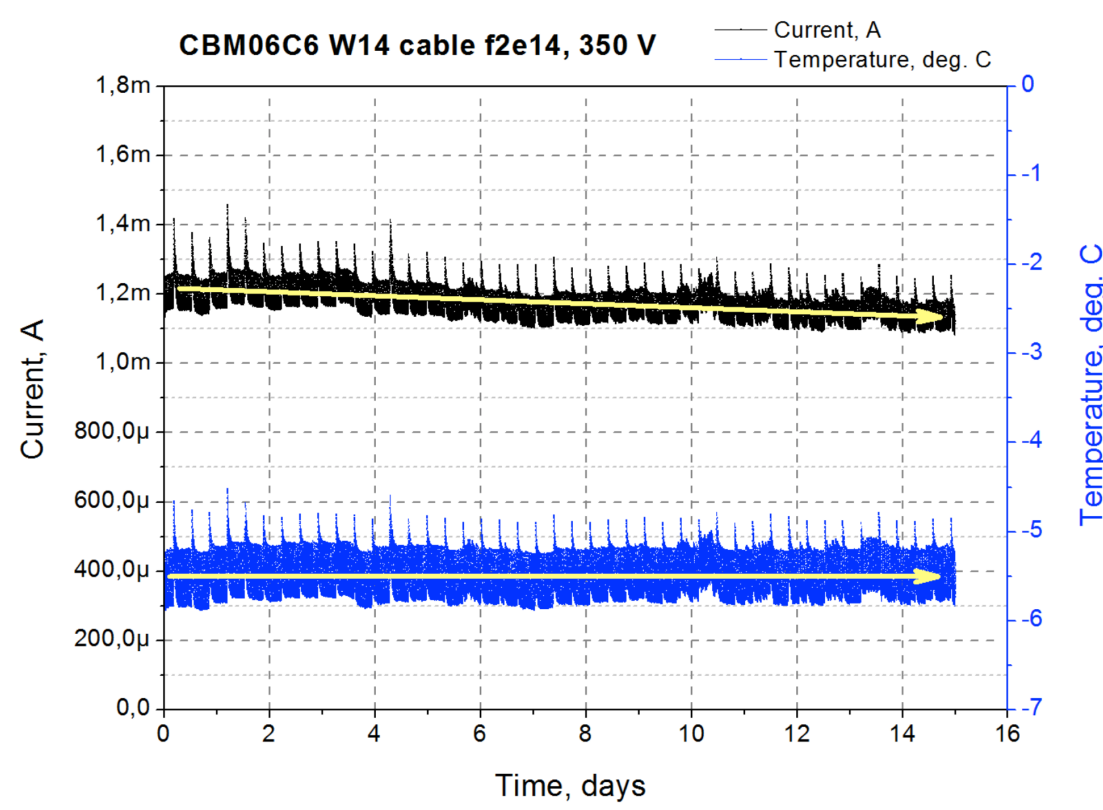
- Full size prototype sensors:  $6 \times 4\text{ cm}$  (Hamamatsu),  $6 \times 6\text{ cm}$  (CiS);
- Strip interconnection schemes: 2nd metal layer (DM), external cable (SMwC);
- Irradiated with protons ( $2 \times 10^{14} n_{eq}/\text{cm}^2$ );
- Thickness: ~290  $\mu\text{m}$  (CiS), ~330  $\mu\text{m}$  (Hamamatsu);
- CiS sensors show less charge collection losses after irradiation;
- DM vs SMwC interconnection: no significant difference.

### Charge collection vs annealing at 80 deg. C



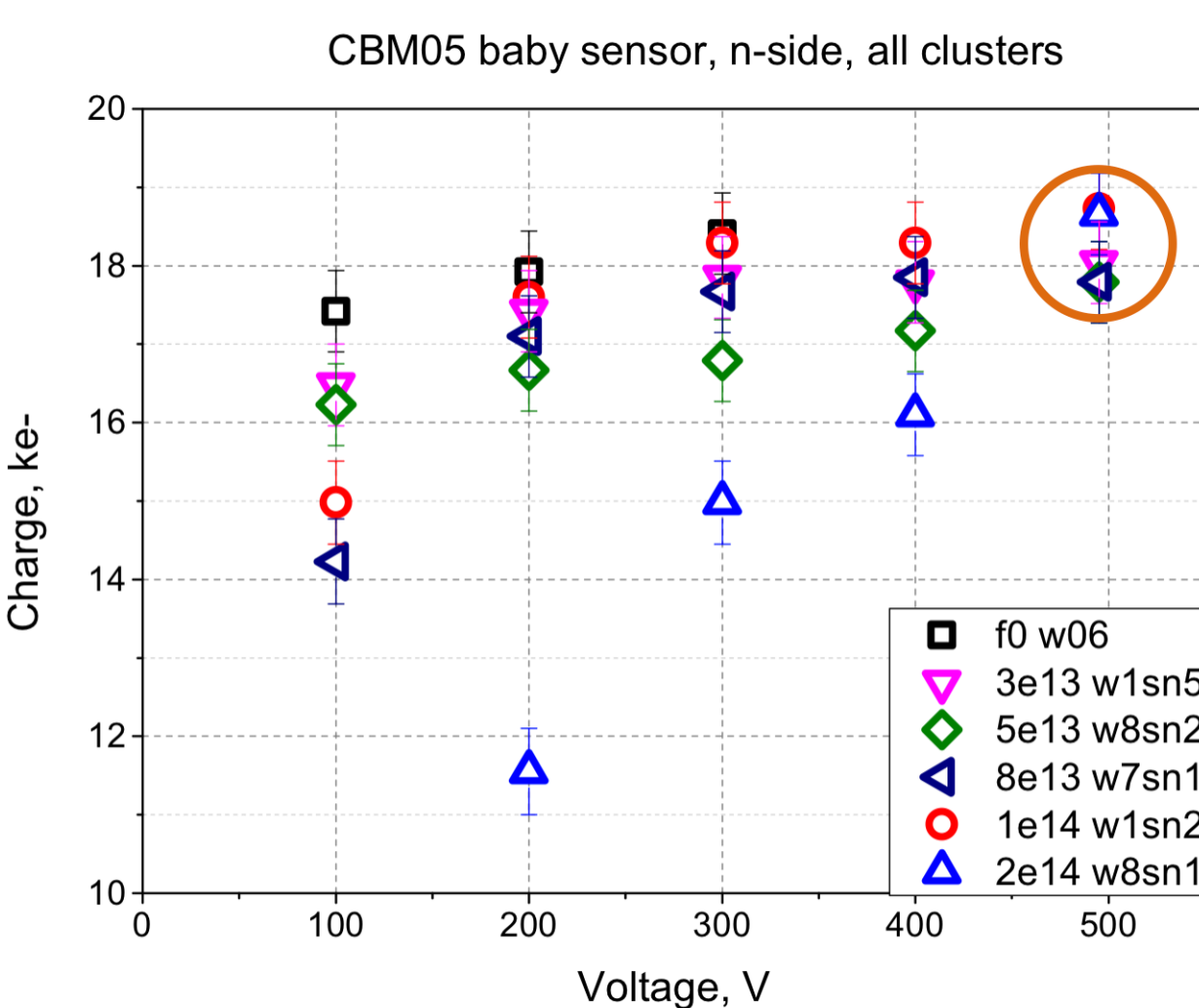
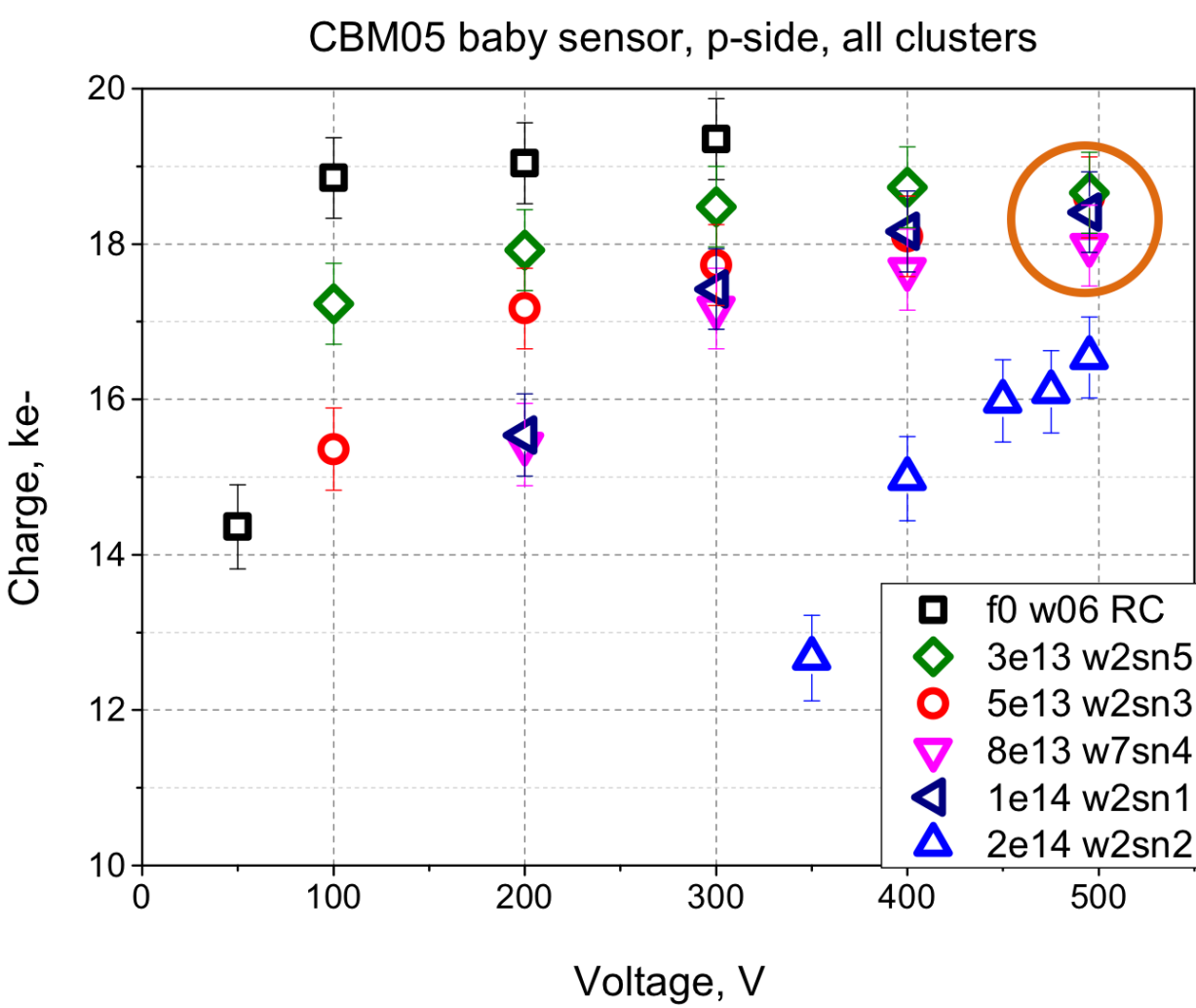
No major changes seen after 120 mins

### Leakage current stability: 15 days

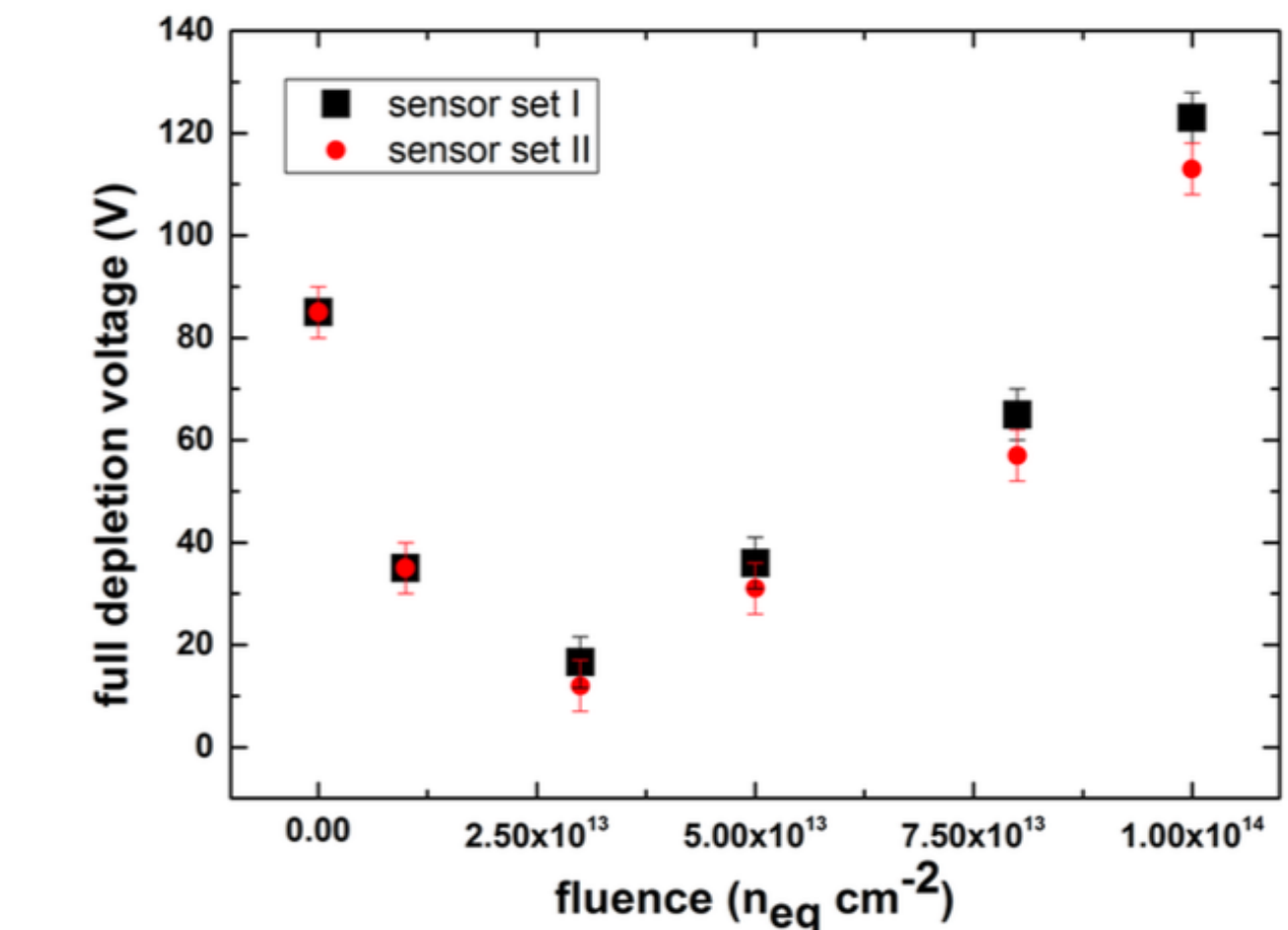


Sensor current over volume scaling with fluence

### Baby sensors charge collection results: p-side (left) and n-side (right)



At 500 V bias applied the collected charge becomes close for most of the sensors



Full depletion voltage vs fluence: type inversion ~  $2 \times 10^{13}$

## Summary

- The developed automated Quality Assurance system allows to identify several strip defects of sensors including pinholes, metal shorts and leaky strips;
- The charge collection of sensors irradiated to fluences from  $1 \times 10^{13}$  to  $2 \times 10^{14} n_{eq}/\text{cm}^2$  degrade with fluence but show similar values at high voltages for both p- and n-sides;
- Charge collected vs annealing time for 120 minutes at 80 deg. C showed close to stable behaviour;
- The stability of the leakage current of irradiated sensors has been monitored for more than 2 weeks showing minor suppression over a long-term period.

[1] Thomas Bergauer, Quality Assurance of the Silicon Strip Sensors for the CMS Tracker, QA Workshop, CERN, 2011.